

FCT ASSEMBLY

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Technical Bulletin RA683 SOLDER PASTE

DESCRIPTION:

RA683 SOLDER PASTE is a rosin activated base solder paste designed similar to the RMA679 but with a higher activation level for difficult to solder boards and/or components. RA683 has the ability to print down to .4mm.

ATTRIBUTES:

- *Excellent printability
- *Good tack time and working life
- *Excellent solderability

PERFORMANCE

PARAMETER	VALUE (English)	VALUE (Metric)
Typical print thickness (20-25 mil pitch)	0.006"-0.008"	150-200 microns
Typical print thickness (<20 mil pitch)	0.004"	100 microns
Minimum pitch	20 mil	500 microns
Minimum pad width	10 mil	250 microns
Stencil life	6-8 hours	
Tack time	6-8 hours	
Slump (per IPC-SP-819):	4 hours@25C<1-%	10 min.@100C<1%

PROCESSING PARAMETERS

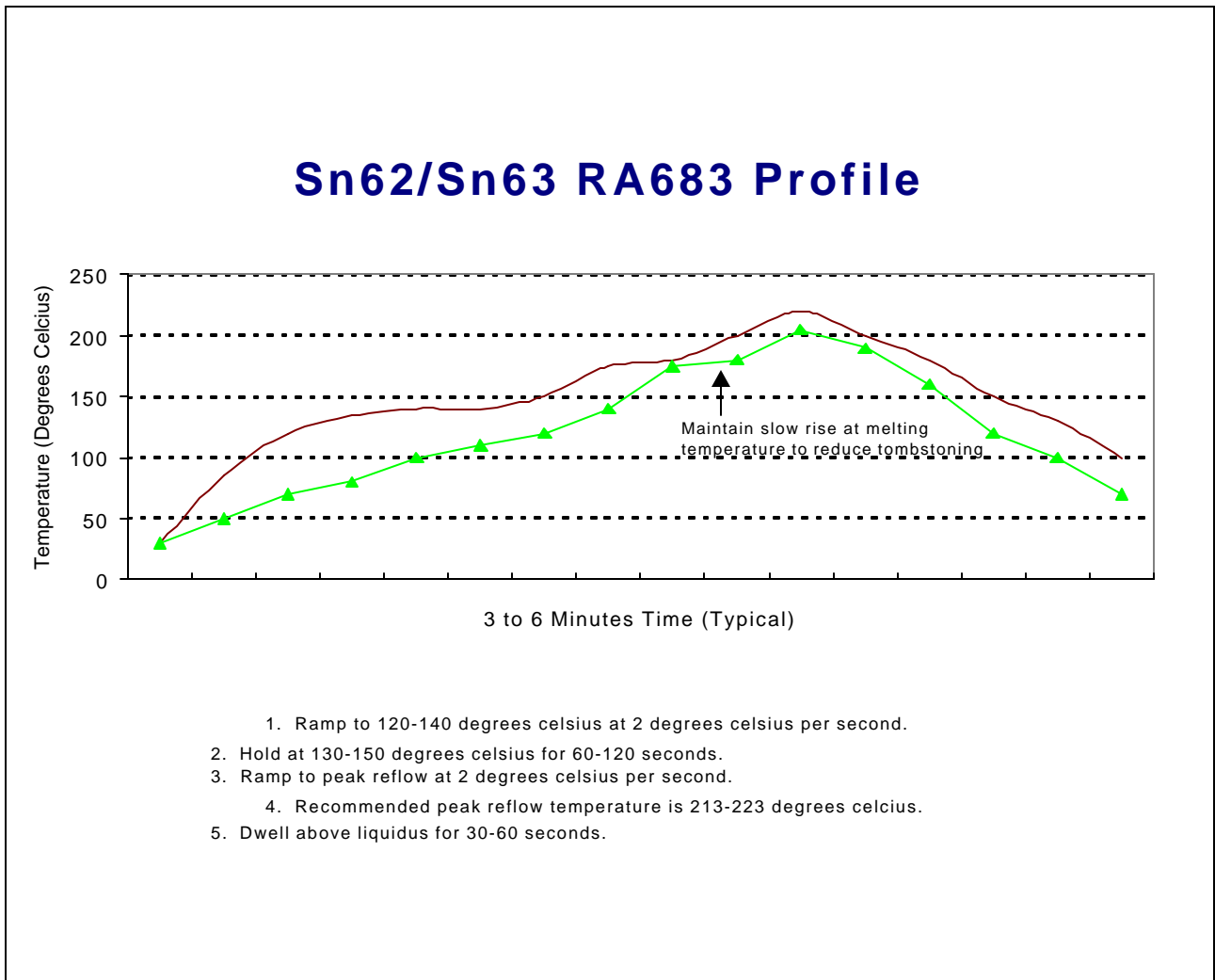
Refrigeration and storage: Do not freeze solder paste. Store below 75F(25C) in a dry location for extending shelf life. Paste may be refrigerated. You must set material out 24 hours prior to use. If the paste does not reach room temperature, the paste may stick to the stencil, not roll into stencil pads, de-wet pads during reflow, outgas in reflow or produce solder balls over the board. Avoid direct sunlight.

Mixing paste: The paste should be mixed after the paste has reached room temperature. Please stir for ~1-2 minutes before applying to the stencil. This will shear the viscosity and insure complete blending.

Handling: The optimum temperature and humidity are 75F or below and 60% or below respectively.

Printing: Typical printing specifications include a squeegee pressure of 200 g/cm, a speed of 25 mm/sec and a durometer of 70-90 or above for 15 mil pitch. Soldering conditions will depend on the size, mass, and component density of the assembly.

Reflow: Reflow should be performed at 30-40C above the liquid temperature of the alloy. This temperature above liquidus should be maintained for 30-60 seconds. Profiles should have less than a 3 minute preheat time above 260F(130C) to insure proper wetting of fine pitch leads.



Cleaning: If cleaning is required, use a semi-aqueous solvent or DI water with a saponifier such as FCT RA2000 (saponifier concentration ~5-10% @~150F(65C))

Available in 250, 500 and 1,000 gram jars and cartridges.
For safety information please refer to the MSDS sheet.

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